

# 客户图

## NOTES:

### 1. FINISH:

- 1.1 HOUSING: LCP BLACK,UL94V-0.
- 1.2 CONTACT: BRASS,GOLD (SEE P/N) PLATED IN CONTACT AREA, 80u" MIN MATTE TIN PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS,80u" MIN. MATTE TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

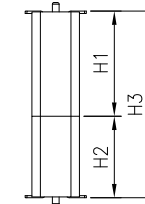
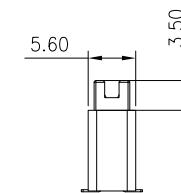
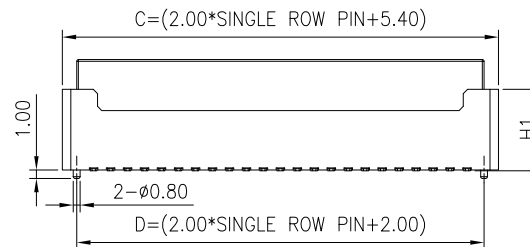
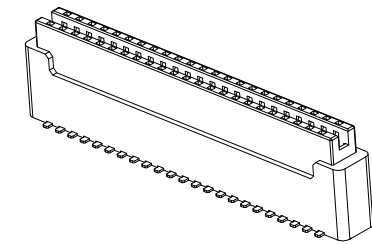
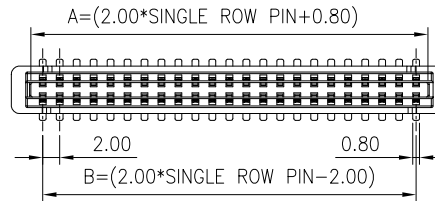
### 2. ELECTRICAL:

- 2.1 CURRENT RATING:3A;
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 500V AC/MINUTE.
- 2.3 CONTACT RESISTANCE: 50mΩ MAX.
- 2.4 INSULATION RESISTANCE: 1000MΩ MIN.
- 2.5 OPERATION TEMPERATURE:-40°C TO +125°C.

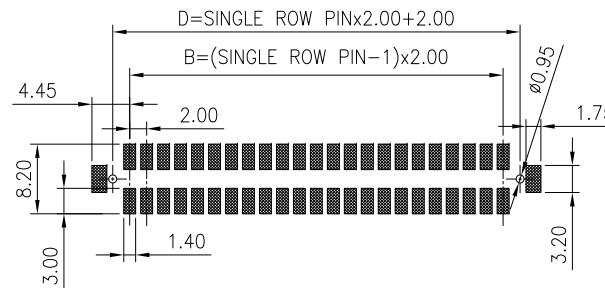
### 3.ORDER INFORMATION:

66G1-F XXX XX 130 C 01

Pin数码	端子电镀:	塑胶高度:	包装方式:
SEE TABLE	S0=Gold Flash/Tin	066=6.60mm	C=脆盘装
006=2*3PIN	S1=1u" Gold/Tin	096=9.60mm	
008=2*4PIN	S2=3u" Gold/Tin		
010=2*5PIN	S3=5u" Gold/Tin		
.....			
040=2*20PIN	S4=10u" Gold/Tin		
050=2*25PIN	S5=15u" Gold/Tin		
060=2*30PIN	S6=30u" Gold/Tin		



MATING HEIGHT



RECOMMENDED PCB LAYOUT(TOP SIDE)  
PCB BOARD TOLFRANCF±0.05

MATING HEIGHT	H1(母头)	H2(公头)	H3(合高)
11.5mm	6.60	4.90	11.50
12.5mm		5.90	12.50
19.00mm		12.40	19.00
32.50mm		25.90	32.50
14.50mm	9.60	4.90	14.50
15.50mm		5.90	15.50
22.00mm		12.40	22.00
35.50mm		25.90	35.50

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	OPERATION		DRAW		FDL		SOLEPIN 东莞市硕品电子有限公司				
					DIM.	TOL	UNIT	mm	SCALE	1:1	PROJ.	SIZE	A4	PART NO.	66G1-FXXXXXXXC01
					X.X	±0.40	DESIGN	Jensen			2019.08.24	Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
					X.XX	±0.25	CHECK	Jack			2019.08.24				
					X.XXX	±0.15	APPROVE	Andy			2019.08.22				
AO		NEW			Angle	±3°						SHEET	1/1	TITLE:	2.00mm BTB 母座直立式 SMT (柱子0.8 柱距+2.0)
												PROJ.	☯	DRAW NO.	SP-084

# 客户图

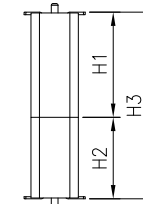
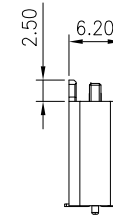
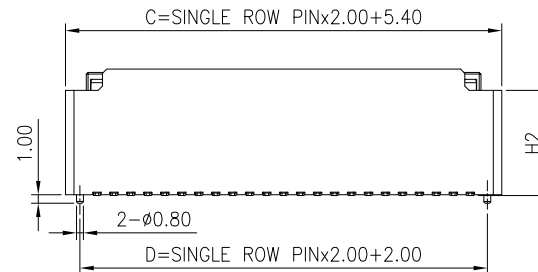
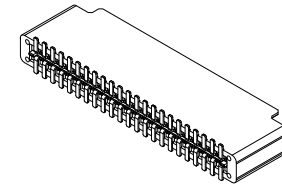
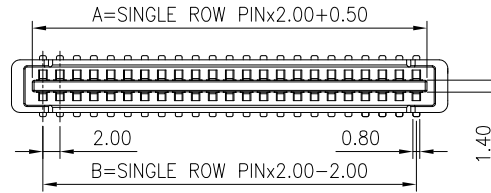
## NOTES:

1. FINISH:
  - 1.1 HOUSING: LCP BLACK,UL94V-0.
  - 1.2 CONTACT: BRASS,GOLD (SEE P/N) PLATED IN CONTACT AREA, 80u" MIN MATTE TIN PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
2. ELECTRICAL:
  - 2.1 CURRENT RATING:3A;
  - 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 500V AC/MINUTE.
  - 2.3 CONTACT RESISTANCE: 50mΩ MAX.
  - 2.4 INSULATION RESISTANCE: 1000MΩ MIN.
  - 2.5 OPERATION TEMPERATURE:-40°C TO +125°C.

## 3.ORDER INFORMATION:

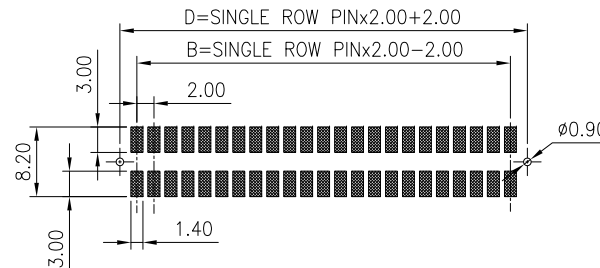
66G1-M XXX XX XXX C 01

Pin数码	端子电镀:	塑胶高度:	包装方式:
SEE TABLE	S0=Gold Flash/Tin	049=4.90mm	C=脆盘装
006=2*3PIN	S1=1u" Gold/Tin	059=5.90mm	
008=2*4PIN	S2=3u" Gold/Tin	124=12.40mm	
010=2*5PIN	S3=5u" Gold/Tin	259=25.90mm	
.....	S4=10u" Gold/Tin		
040=2*20PIN	S5=15u" Gold/Tin		
050=2*25PIN	S6=30u" Gold/Tin		
060=2*30PIN			



MATING HEIGHT

MATING HEIGHT	H1 (母头)	H2 (公头)	H3 (总高)
11.5mm	6.60	4.90	11.50
12.5mm		5.90	12.50
19.00mm		12.40	19.00
32.50mm	9.60	25.90	32.50
14.50mm		4.90	14.50
15.50mm		5.90	15.50
22.00mm		12.40	22.00
35.50mm		25.90	35.50



RECOMMENDED PCB LAYOUT(TOP SIDE)  
PCB BOARD TOLFRANCF±0.05

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	OPERATION	DRAW	WLY	DATE	SOLEPIN 东莞市硕品电子有限公司 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.				
AO		NEW			X.X ±0.40	DESIGN	Jensen	2019.08.22	SIZE	A4	PART NO.	66G1-MXXXXXXXXXC01	
					X.XX ±0.25	CHECK	Jack	2019.08.22	SHEET	1/1	TITLE:	2.00mm BTB 公头直立式 SMT (柱子0.8 柱距+2.0)	
					X.XXX ±0.15	APPROVE	Andy	2019.08.22	PROJ.	☉	DRAW NO.	SP-081	
					Angle ±3°				UNIT	mm	SCALE	1:1	
					DIM. TOL								